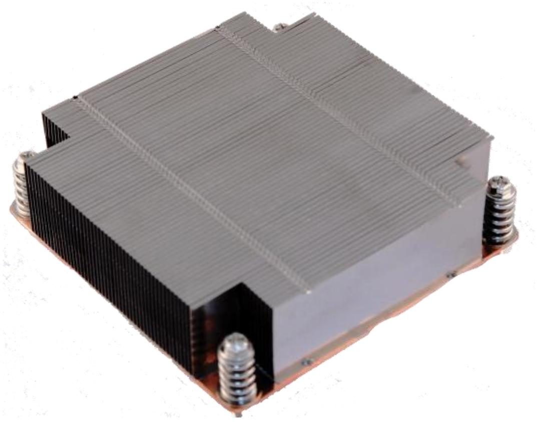
VEL-00004-N1-GP



Application

LGA 2011 (Socket R Square) M4

Test result:

	130W	150W
Flow (CFM)	Rca (℃/W)	Rca (℃/W)
10	0.2529	0.2626
15	0.2031	0.2109
16	0.199	0.2043
20	0.1796	0.1821
25	0.1638	0.1687
30	0.1541	0.1583
35	0.1472	0.1491
40	0.1423	0.1423
45	0.1374	0.1383
50	0.1343	0.1353

Safety

CE c UL US

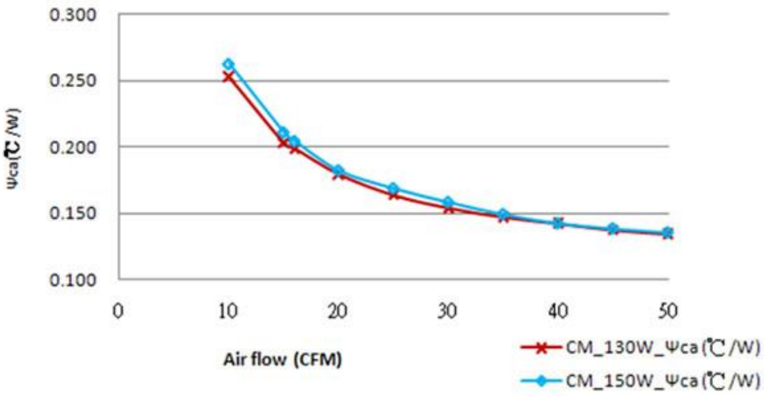
Thermal and Mechanical Spec

Thermal performance for 130W/150W CPU

HSK Assembly Weight: 205 g

CPU Loading: 65 lbf

Performance Curve



Component Specifications

Application System	1U Form Factor Passive Solution
Material	Aluminum Fin + Vapor Chamber Base
Dimension	90L × 90W × 26.5H mm
Fin	Thick=0.2mm, Pitch=1.38mm, 66 fin
Thermal interface Material	Shin Etsu 7783 (36 × 36 mm)

*All readings are typical values at rated voltage.

*Specifications are subjected to change without notice.